CLAIMS

1. A tape for wafer processing, comprising:

a long release film;

a pressure-sensitive adhesive film having a label part provided on a first face of the release film and having a predetermined shape corresponding to the shape of a ring frame for dicing, and a peripheral part surrounding the outer side of the label part; and

support members provided at two ends in the transverse direction of the release film, the support members being provided on a second face on the opposite side of the first face having the pressure-sensitive adhesive film provided thereon,

wherein the support members are each provided so as to have a region overlapping with the label part, with the release film being disposed therebetween, and the maximum width of the region overlapping with the label part, the maximum width extending in the transverse direction of the release film, is 25 mm or less,

wherein the pressure-sensitive adhesive film has an arithmetic surface roughness Ra of 0.3 μm or less on the side not in contact with the release film, and the support members each have a thickness of 30 to 150 μm.

2. The tape for wafer processing according to claim 1, wherein the support members are provided continuously along the longitudinal direction of the release film.

3. The tape for wafer processing according to any one of claims 1 to 2, wherein the support members each have a laminated structure including two or more layers.

4. The tape for wafer processing according to any one of claims 1 to 3, wherein the support members are formed from a tacky adhesive tape obtained by applying a tacky adhesive on a resin film base material selected from the group consisting of polyethylene terephthalate, polypropylene, and high-density polyethylene.